

IN THE CLAIMS

1. (previously presented) A composite structure comprising:

a base having a first side and a second side, the first side having a patterned surface structure including at least one aperture extending through the base between the first side and the second side;

a printed circuit board including at least one raised circuit component elevated from a board portion of the printed circuit board and the at least one raised circuit component extending into the at least one aperture and forming a space between an edge surface of the at least one aperture and the at least one raised circuit component;

an adhesive portion in the at least one aperture that extends between the first and second sides of the base and between the edge surface of the at least one aperture and the at least one raised circuit component to fill the space between the at least one raised circuit component and the edge surface of the at least one aperture of the base; and

an adhesive layer between the base and the board portion of the printed circuit board bonding the base to the printed circuit board.

2. (cancelled)

3. (currently amended) The structure according to claim 1 wherein the adhesive layer between the base and the board portion forms a first adhesive layer and comprising a second adhesive ~~portion~~layer between the printed circuit board and a shield to connect the shield to the printed circuit board. |

4. (previously presented) A structure comprising:

a base having a first side and a second side, the first side having a patterned surface structure including at least one aperture extending through the base between the first side and the second side;

a printed circuit board including at least one raised circuit component elevated from a

- board portion of the printed circuit board and the at least one raised circuit component extending into the at least one aperture and forming a space between an edge surface of the at least one aperture and the at least one raised circuit component, wherein the printed circuit board has an upright connector;
- an adhesive portion in the at least one aperture that extends between the first and second sides of the base and between the edge surface of the at least one aperture and the at least one raised circuit component to fill the space between the at least one raised circuit component and the edge surface of the at least one aperture of the base; and
- an adhesive portion between the upright connector and an edge surface of the base.
5. (previously presented) The structure according to claim 1 wherein an overall thickness of the structure is less than 3.3 mm.
6. (previously presented) The structure according to claim 5 wherein the base has a portion having a thickness of between 0.2 mm and 0.3 mm.
7. (previously presented) A composite structure for a data storage device comprising:
- a base having a first side and a second side;
  - a printed circuit board spaced from the base to form a gap between the printed circuit board and the base;
  - a shield spaced from the printed circuit board to form a gap between the printed circuit board and the shield; and
  - a first adhesive portion filling the gap between the printed circuit board and the base to connect the printed circuit board to the base, and a second adhesive portion filling the gap between the printed circuit board and the shield to connect the shield to the printed circuit board.
8. (previously presented) The structure according to claim 7 wherein the base includes at least one aperture and the printed circuit board includes at least one circuit component extending into the at least one aperture and comprising an adhesive portion in the at least one aperture between

an edge surface of the at least one aperture and the at least one circuit component.

9. (cancelled).

10. (cancelled)

11. (previously presented) The structure according to claim 7 wherein an overall thickness of the structure is less than 3.3 mm.

12. (previously presented) The structure according to claim 11 wherein the base has a portion having a thickness of between 0.2 mm and 0.3 mm.

13. (cancelled)

14. (cancelled)

15. (cancelled)

16. (cancelled)

17. (previously presented) The structure according to claim 4 wherein at least one of the adhesive portions is an epoxy adhesive.

18. (previously presented) The structure according to claim 1 wherein the adhesive portion is an epoxy adhesive.

Claims 19-20 (cancelled).

21. (previously presented) The composite structure of claim 8 wherein the at least one aperture extends through the base between the first side and the second side of the base.

22. (currently amended) The composite structure of claim 7 wherein the printed circuit board includes at least one connector and comprising a third adhesive portion between an upright surface of the base and the at least one connector.

23. (cancelled)

24. (cancelled)

25. (cancelled)

26. (previously presented) The structure of claim 1 wherein the base includes a base portion having a base thickness of about 0.3mm or less.

27. (previously presented) The structure of claim 4 wherein the base includes a base portion having a base thickness of about 0.3mm or less.

28. (previously presented) The structure of claim 4 and comprising an adhesive layer between the base and the board portion of the printed circuit board bonding the base to the printed circuit board.

29. (previously presented) The structure of claim 1 and comprising at least one lead extending through the adhesive layer and soldered to a solder pad on the printed circuit board.

30. (previously presented) The structure of claim 1 wherein the adhesive portion and the adhesive layer are a thermally conductive epoxy.

31. (previously presented) The structure of claim 4 wherein each adhesive portion is a thermally conductive epoxy.

32. (previously presented) The structure of claim 1 and comprising a tape seal on the at least one aperture.